



# **MT3336 GPS Host-Based Solution Data Sheet**

Version: 1.06  
Release date: 2011-10-26

© 2011 MediaTek Inc.

This document contains information that is proprietary to MediaTek Inc.

Unauthorized reproduction or disclosure of this information in whole or in part is strictly prohibited.

Specifications are subject to change without notice.

## Document Revision History

Revision	Date	Author	Description
0.01	2010/11/08	Loris Li	Update TFBGA ball map and pin description
0.02	2010/11/30	Loris Li	Update pin-mux and strap information
0.03	2010/12/08	Loris Li	Update RF part description
0.04	2010/12/10	Loris Li	Update System overview
0.05	2010/12/10	Loris Li	Update RF part electrical characteristics
0.06	2010/12/14	Loris Li	Update analog part electrical characteristics
0.07	2010/12/17	Loris Li	Update RF LDO electrical characteristics
0.08	2010/12/19	Loris Li	Update power scheme
0.09	2010/12/21	Loris Li	Add RTC domain power scheme
0.10	2010/12/21	Loris Li	Modify according to YC Chien's suggestion
0.11	2010/12/21	Loris Li	Update by JN Yang about UART baud rate and SPI/I2C clock rate
0.12	2010/12/24	Loris Li	Update RF related description
0.13	2010/12/24	Loris Li	Update system overview by Andy Lee
0.14	2010/12/29	Loris Li	Update host interface related description
0.15	2010/12/30	Loris Li	Update power scheme
0.16	2011/01/03	Loris Li	Update block diagram
0.17	2011/01/04	Loris Li	Update crystal frequency range
0.18	2011/01/05	Loris Li	Update external LNA related information
0.19	2011/01/05	Loris Li	Update power scheme diagram and EEPROM I2C interface timing diagram
0.20	2011/01/07	Loris Li	Update power related description
0.21	2011/01/07	Loris Li	Update footprint size
0.22	2011/01/20	Loris Li	Change minimum input power to 2.7V
0.23	2011/01/20	Loris Li	Sync PIN naming of DC characteristic table and change minimum input power to 2.8V
0.24	2011/01/24	Loris Li	Update power scheme and RF information
0.25	2011/02/08	Loris Li	Update description of 32K_OUT pin
0.26	2011/02/11	Loris Li	Add ECLK and SYNC description
0.27	2011/03/15	Loris Li	Add 1.2V IO characteristic for TIMER and 32K_OUT and update serial flash size to 128Mb
0.28	2011/03/15	Loris Li	Remove description about factory testing and internal SRAM size
0.29	2011/03/22	Loris Li	Remove description about strap function tcxo on/off
0.30	2011/03/30	Loris Li	1. Update RTC leakage information to typ 2. Update package dimensions information 3. Update RF related descriptions
0.31	2011/04/01	Loris Li	1. Remove Vcc description in 6.3.1 2. Add strap pin tldo_sw_sel description 3. Change MAX of VIH for TIMER and 32K_OUT to 3.6V
0.32	2011/04/07	Loris Li	Change description in 5.20 about CLDO off
0.33	2011/04/12	Loris Li	Add RF LNA MIN of VGA gain and MAX of noise figure

0.34	2011/04/27	Loris Li	Update package dimension total height to max 1mm
0.35	2011/05/19	Loris Li	Change RF LDO related voltage description
0.36	2011/05/23	Loris Li	Add reset controller power on reset diagram
0.37	2011/05/25	Linda Chen	Update to MTK standard format
0.38	2011/06/10	Loris Li	Change LDO $I_{max}$ related description
0.39	2011/06/13	Loris Li	Review electrical characteristics
0.40	2011/06/20	Loris Li	Review feature and internal description.
0.41	2011/07/01	Loris Li	Update TCXO_SW SPEC
0.42	2011/07/08	Loris Li	1. Update QFN POD related information 2. Update QFN current information
1.0	2011/07/13	Loris Li	1. Update Power scheme for QFN by Peter 2. Review description by YC
1.01	2011/08/24	Loris Li	Change AVDD_RFCORE $V_{min}$ SPEC from 1.14 to 1.16
1.02	2011/08/25	Loris Li	Add top mark description
1.03	2011/09/09	Loris Li	Add power up sequence diagram for external LDO mode
1.04	2011/09/16	Loris Li	Add power up sequence diagram for low power/cost mode
1.05	2011/09/19	Loris Li	Remove power up sequence diagram for low power/cost mode and add power on/off reset behavior diagram in chapter 5.8.
1.06	2011/10/26	Loris Li	Update top mark

## Table of Contents

<b>Document Revision History .....</b>	<b>2</b>
<b>Table of Contents .....</b>	<b>4</b>
<b>1 System Overview .....</b>	<b>6</b>
1.1 General descriptions .....	6
1.2 Features .....	7
<b>2 Pin Assignment and Descriptions .....</b>	<b>8</b>
2.1 Pin assignment (top view) .....	8
2.2 Pin descriptions .....	9
<b>3 Block Diagrams .....</b>	<b>12</b>
3.1 Architecture of single-chip receiver .....	12
3.2 Functional block diagram (RF part) .....	12
<b>4 MT3336 RF Part .....</b>	<b>13</b>
4.1 LNA/Mixer .....	13
4.2 VCO/Synthesizer .....	13
4.3 IF CSF .....	13
4.4 PGA .....	13
4.5 ADC .....	13
<b>5 MT3336 Digital Part .....</b>	<b>14</b>
5.1 Boot ROM .....	14
5.2 Battery backed-up memory .....	14
5.3 SMPS .....	15
5.4 Timer function .....	15
5.5 GPIO in RTC domain .....	15
5.6 Low power detection .....	15
5.7 Clock module .....	15
5.8 Reset controller .....	15
5.9 Host interface .....	16
5.9.1 UART .....	16
5.9.2 SPI .....	17
5.9.3 I2C .....	17
5.10 Interrupt control unit .....	17
5.11 GPIO unit .....	17
5.12 PPS .....	17
5.13 ECLK .....	17
5.14 SYNC .....	18
5.15 Power scheme .....	18
<b>6 Electrical Characteristics .....</b>	<b>21</b>
6.1 DC characteristics .....	21
6.1.1 Absolute maximum ratings .....	21

6.1.2	Recommended operating conditions .....	21
6.1.3	General DC characteristics .....	22
6.1.4	DC electrical characteristics for 2.8 volts operation.....	22
6.1.5	DC electrical characteristics for 1.8 volts operation.....	22
6.1.6	DC electrical characteristics for 1.2 volts operation (for TIMER and 32K_OUT)....	22
6.2	Analog related characteristics .....	23
6.2.1	SMPS DC characteristics.....	23
6.2.2	TCXO LDO DC characteristics .....	23
6.2.3	TCXO SWITCH DC characteristics .....	23
6.2.4	1.2 volts core LDO DC characteristics.....	24
6.2.5	1.2 volts RTC LDO DC characteristics .....	24
6.2.6	32 KHz crystal oscillator (XOSC32).....	24
6.3	RF related characteristics.....	24
6.3.1	DC electrical characteristics for RF part .....	24
6.3.2	RX chain from LNA to PGA, before ADC.....	25
6.3.3	Receiver front-end part (LNA only) .....	25
6.3.4	Mixer and channel selection filter (CSF).....	25
6.3.5	Programmable gain amplifier (PGA).....	26
6.3.6	2-bit and 4-bit quantizer (ADC) .....	26
6.3.7	Integrated synthesizer.....	26
6.3.8	Crystal oscillator (XO).....	26
<b>7</b>	<b>Interface Characteristics .....</b>	<b>27</b>
7.1	RS-232 interface timing .....	27
7.2	SPI interface timing .....	27
7.3	I2C interface timing.....	28
<b>8</b>	<b>Package Description .....</b>	<b>29</b>
8.1	Top mark.....	29
8.2	Package dimensions .....	30

## Lists of Figures

Figure 3-1:	MT3336 system block diagram.....	12
Figure 3-2:	MT3336 RF functional block diagram.....	12
Figure 5-1:	RTC with internal RTC LDO application circuit 1.....	14
Figure 5-2:	RTC with internal RTC LDO application circuit 2.....	14
Figure 5-3:	Power on reset diagram .....	16
Figure 5-4:	Power on/off reset behavior.....	16
Figure 5-5:	Flow diagram of SYNC function .....	18
Figure 5-6:	Power supply connection (low power).....	19
Figure 5-7:	Power supply connection (low cost) .....	19
Figure 5-8:	Power supply connection (external LDO).....	20
Figure 5-9:	Power up sequence for external LDO mode .....	20
Figure 7-1:	Timing diagram of RS-232 interface .....	27
Figure 7-2:	Timing diagram of SPI interface .....	28
Figure 7-3:	Timing diagram of HOST I2C interface.....	28

## 1 System Overview

---

### 1.1 General descriptions

MT3336 is a high-performance single-chip GPS solution which includes on-chip CMOS RF and digital baseband. It is able to achieve the industry's highest level of sensitivity, accuracy and Time-to-First-Fix (TTFF) with the lowest power consumption in a small-footprint lead-free package. Its small footprint and minimal BOM requirement provide significant reductions in the design, manufacturing and testing resource required for portable applications.

With built-in LNA to reach total NF to 2.2 dB, you can eliminate antenna requirement and do not need external LNA. With its on-chip image-rejection mixer, the spec of external SAW filter is alleviated. With an on-chip automatic center frequency calibration band pass filter, an external filter is not required. The on-chip power management design allows MT3336 to be easily integrated into your system without extra voltage regulator. With both linear and a highly efficient switching type regulator embedded, MT3336 allows direct battery connection and does not need any external LDO, which gives customers plenty of choices for the application circuit.

Up to 12 multi-tone active interference cancellers (ISSCC2011 award) offer you more flexibility in system design. The integrated PLL with Voltage Controlled Oscillator (VCO) provides excellent phase noise performance and fast locking time. A battery backed-up memory and a real-time clock are also provided to accelerate acquisition at the system restart-up.

MT3336 supports up to 210 PRN channels. With 66 search channels and 22 simultaneous tracking channels, MT3336 acquires and tracks satellites in the shortest time even at indoor signal levels. MT3336 supports various location and navigation applications, including autonomous GPS, SBAS ranging (WAAS, EGNOS, GAGAN, and MSAS), QZSS, DGPS (RTCM) and AGPS.

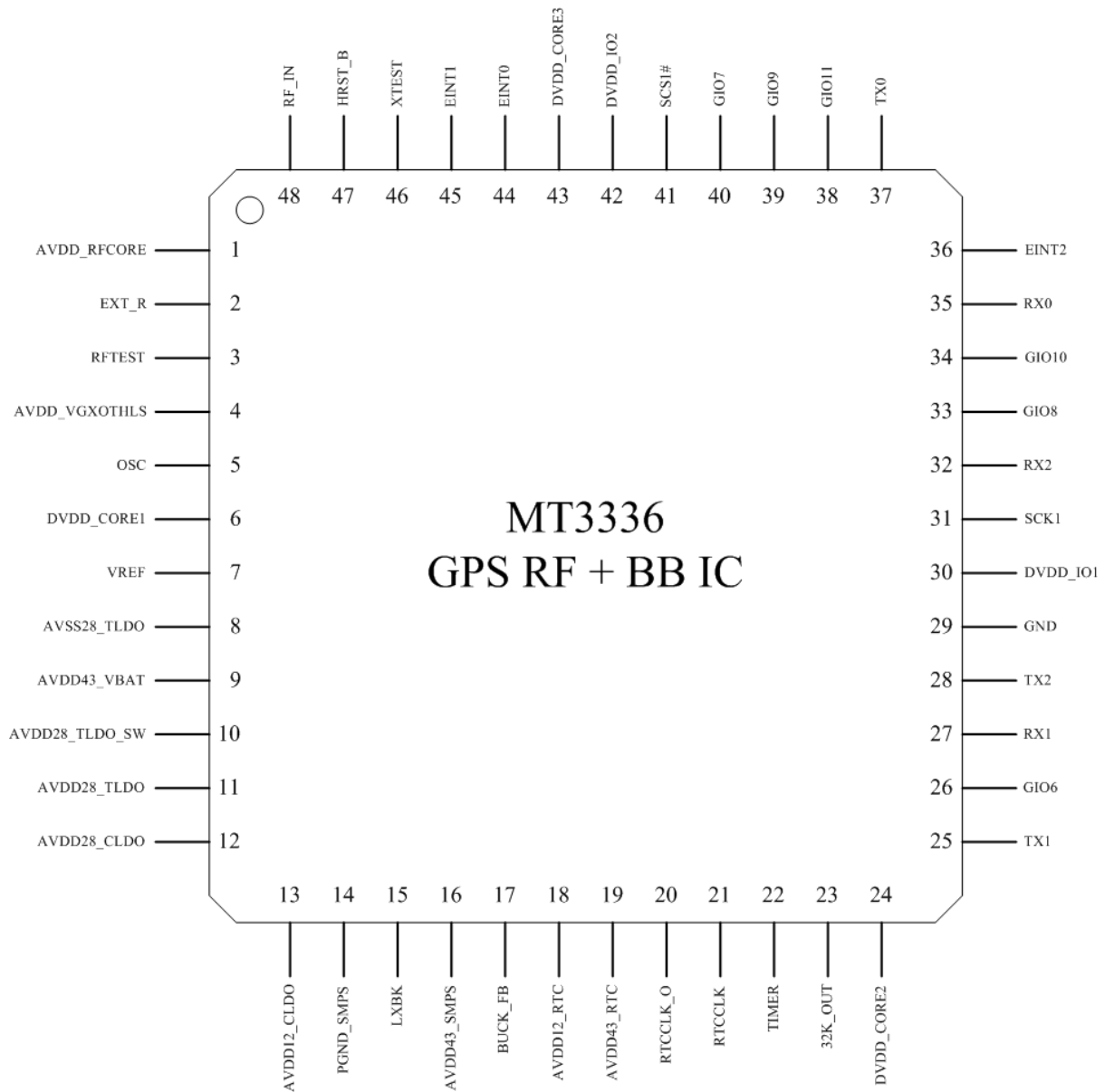
Through MT3336's excellent low-power consumption characteristic (acquisition 24 mW, track 17 mW), power sensitive devices, especially portable applications, you will not need to worry about the operating time anymore and can have more fun. Combined with many advanced features including AlwaysLocate™, HotStill™, and EPO™ function, MT3336 provides always-on position with minimal average power consumption. The great features provide you supreme experiences for portable applications such as DSC, cellular phone, PMP and gaming devices.

## 1.2 Features

- Specifications
  - 22 tracking / 66 acquisition-channel GPS receiver
  - Supports up to 210 PRN channels
  - Supports multi-GNSS incl. QZSS, SBAS ranging
  - Supports WAAS/EGNOS/MSAS/GAGAN
  - 12 multi-tone active interference cancellers (ISSCC2011 award)
  - RTCM ready
  - Indoor and outdoor multi-path detection and compensation
  - Supports FCC E911 compliance and A-GPS
  - Max. fixed update rate up to 5 Hz
- Advanced software features
  - AlwaysLocate™ advanced location awareness technology
  - EPO™/HotStill™ orbit prediction
- Reference oscillator
  - TCXO
    - Frequency: 16.368 MHz, 12.6 ~ 40.0 MHz
    - Frequency variation: ±2.0 ppm
  - Crystal
    - Frequency: 26 MHz, 12.6 ~ 40.0 MHz
    - Frequency accuracy: ±10 ppm
- RF configuration
  - 4-bit IF signal
  - SoC, integrated in single chip with CMOS process
- Pulse-per-second (PPS) GPS time reference
  - Adjustable duty cycle
  - Typical accuracy: ±10 ns
- Power scheme
  - A 1.8 volts SMPS build-in SOC
  - Direct lithium battery connection (2.8 ~ 4.3 volts)
  - Self build 1.2 volts RTC LDO, 1.2 volts core LDO, and 2.8 volts TCXO LDO
- Build-in reset controller
  - Does not need of external reset control IC
- Internal real-time clock (RTC)
  - 32.768 KHz ± 20 ppm crystal
  - Timer pin for external device on/off control
  - 1.2 volts RTC clock output
  - Supports external pin to wake up MT3336
- Serial interface
  - 3 UARTs
  - SPI
  - I2C
  - GPIO interface (up to 16 pins)
- Superior sensitivities
  - Acquisition: -148 dBm (cold) / -163 dBm (hot)
  - Tracking: -165 dBm
- Ultra-low power consumption
  - Acquisition: 24 mW
  - Tracking: 17 mW
  - AlwaysLocate™: 3 mW
- Package
  - QFN: 6mm x 6mm, 48 ball
- Slim hardware design
  - 52 mm<sup>2</sup> solution footprint with all software features inside
  - 9 passive external components

## 2 Pin Assignment and Descriptions

### 2.1 Pin assignment (top view)





## 2.2 Pin descriptions

Pin#	Symbol	Type	Description
<b>System interface (2 pins)</b>			
47	HRST_B	2.8V LVTTTL input 75K pull-up, SMT	System reset. Active low
46	XTEST	2.8V LVTTTL input 75K pull-down, SMT	Test mode. <i>Must keep low in normal mode.</i>
<b>Peripheral interface (8 pins)</b>			
35	RX0/MM_I2CC/H_SPI_SI	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	Serial input for UART 0 Default: 75K pull-up Default: 8mA driving
37	TX0/MM_I2CD/H_SPI_SO	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	Serial output for UART 0 Default: 75K pull-up Default: 8mA driving
27	RX1/H_SPI_SCK/CTS0/MM_I2CC/CXO_TSENS/GIO0	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	Serial input for UART 1 Default: 75K pull-up Default: 8mA driving
25	TX1/TXIND/RTS0/MM_I2CD/CXO_CS/GIO1	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	Serial output for UART 1 Default: 75K pull-up Default: 8mA driving
32	RX2/SPI_SI/DBG_RX/BSI_CK/GIO2	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	Serial input for UART 2 Default: 75K pull-up Default: 8mA driving
28	TX2/SPI_SO/DBG_TX/GIO3	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	Serial output for UART 2 Default: 75K pull-up Default: 8mA driving Strap pin tldo_sw_sel (not supported on ES1/ES2 version IC) 1'b0: AVDD28_TLDO_SW output 1.8V 1'b1: AVDD28_TLDO_SW output 2.8V
31	SCK1/SPI_SCK/GIO4	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	SPI clock output Default: 75K pull-up Default: 8mA driving Strap pin clk_sel[0] <b>Clk_sel[1:0] Mode</b> 2'b00: XTAL mode 2'b01: External clock mode 2'b10: TCXO mode 2'b11: 16.368MHz TCXO mode
41	SCS1#/SPI_SCS#/BSI_DATA/SYNC_PULSE/GIO5	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	SPI slave selection 1 Default: 75K pull-up Default: 8mA driving Strap pin clk_sel[1]
<b>Debugging interface (6 pins)</b>			

Pin#	Symbol	Type	Description
26	BSI_CK/MM_I2CC/ECLK/GIO6	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	GPIO6 Default: 75K pull-down Default: 8mA driving
40	BSI_CS/MM_I2CD/DUTY_CYCLE/PPS/GIO7	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	GPIO7 Default: 75K pull-down Default: 8mA driving
33	FRAME_SYNC/DBG_RX/GIO8	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	GPIO8 Default: 75K pull-down Default: 8mA driving
39	PPS/DBG_TX/GIO9	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	GPIO9 Default: 75K pull-up Default: 8mA driving Strap pin host_sel[0] <b>Host_sel[1:0] Interface</b> 2'b00: I2C 2'b01: UART MEIF 2'b10: SPI 2'b11: UART
34	CXO_CS/GIO10	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	GPIO10 Default: 75K pull-up Default: 8mA driving Strap pin host_sel[1]
38	H_SPI_SCS#/CXO_TSENS/ SYNC_PULSE/GIO11	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	GPIO11 Default: 75K pull-up Default: 8mA driving
<b>External system interface (4 pins)</b>			
44	EINT0/MM_I2CC/BSI_CS/GIO12	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	External interrupt 0 Default: 75K pull-down Default: 8mA driving
45	EINT1/MM_I2CD/PPS/BSI_DATA/GIO13	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	External interrupt 1 Default: 75K pull-down Default: 8mA driving
36	EINT2/DBG_RX/PPS/GIO14	2.8V, LVTTTL I/O PPU, PPD, SMT 2mA ~ 16mA PDR	External interrupt 2 Default: 75K pull-up Default: 8mA driving
<b>RTC interface (6 pins)</b>			
19	AVDD43_RTC	Analog power	RTC LDO input
18	AVDD12_RTC	Analog power	RTC LDO output
21	RTCCLK	Analog input	RTC 32KHz XTAL input
20	RTCCLK_O	Analog output	RTC 32KHz XTAL output
23	32K_OUT/DR_IN	1.2V LVTTTL I/O PPU, PPD, SMT 4mA, 8mA, 12mA, 16mA PDR	RTC domain GPIO pin, can be programmed to 32KHz clock output or DR wake-up signal input Default: 75K pull-down Default: 16mA driving

Pin#	Symbol	Type	Description
22	TIMER	1.2V LVTTTL I/O open drain, SMT 4mA, 8mA, 12mA, 16mA PDR	Wake up other devices from RTC. If this pin is not used, tie it to the ground.
<b>RF &amp; analog</b>			
1	AVDDRF_CORE	RF power	1.8V supply for RF core circuits
2	EXT_R	Analog	External R connection for R calibration
3	RFTEST	Analog signal	RF testing signal
4	AVDD_BGXOTHLS	RF power	1.8V supply for XTAL OSC, bandgap, Thermal sensor and level shifter
5	OSC	Analog signal	Input for crystal oscillator or TCXO
48	RF_IN	RF signal	LNA RF Input pin
6	DVDD_CORE1	Digital power	Digital 1.2V core power input
24	DVDD_CORE2	Digital power	Digital 1.2V core power input
43	DVDD_CORE3	Digital power	Digital 1.2V core power input
30	DVDD_IO1	Digital power	Digital 1.8/2.8V IO power input
42	DVDD_IO2	Digital power	Digital 1.8/2.8V IO power input
29	GND	Digital ground	Digital ground
7	VREF	Analog	Bandgap output pin. Must add 1uF decoupling cap on EVB.
8	AVSS28_TLDO	Analog ground	GND pin for TCXO LDO and start-up block
9	AVDD43_VBAT	Analog power	TCXO LDO input pin. always be powered by external source. UVLO will detect this PIN to check power status.
10	AVDD28_TLDO_SW	Analog power	TCXO power switch output pin
11	AVDD28_TLDO	Analog power	TCXO LDO output pin
12	AVDD28_CLDO	Analog power	Core LDO input pin. Always powered by external source or SMPS
13	AVDD12_CLDO	Analog power	Core LDO output pin
14	PGND_SMPS	SMPS	SMPS GND pin
15	LXBK	SMPS	SMPS output pin
16	AVDD43_SMPS	SMPS	SMPS input pin.
17	BUCK_FB	SMPS	SMPS feedback pin

**Notes:**

PPU = Programmable pull-up  
 PPD = Programmable pull-down  
 PSR = Programmable slew rate  
 PDR = Programmable driving

### 3 Block Diagrams

#### 3.1 Architecture of single-chip receiver

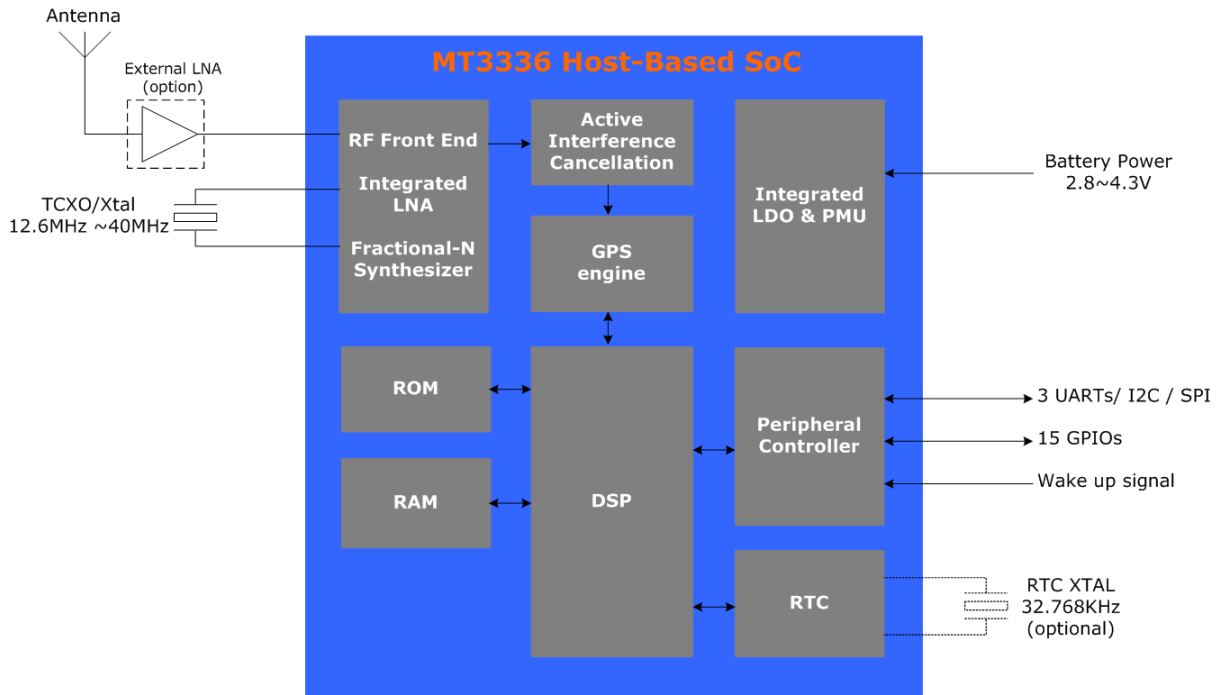


Figure 3-1: MT3336 system block diagram

#### 3.2 Functional block diagram (RF part)

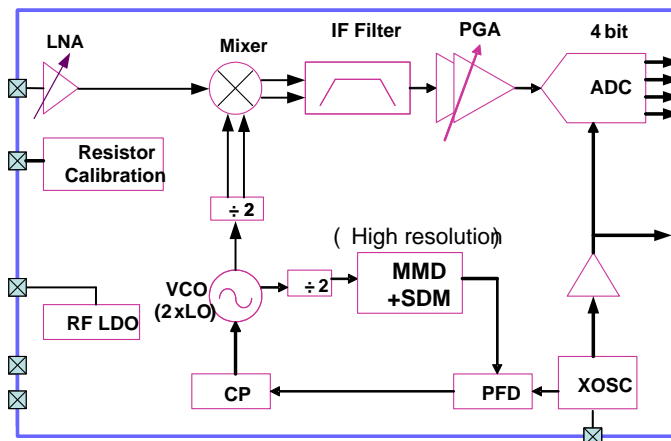


Figure 3-2: MT3336 RF functional block diagram

## 4 MT3336 RF Part

---

### 4.1 LNA/Mixer

Upon receiving RF input signal in through either GPS antenna to internal LNA or external antenna and LNA, the mixer down converts the amplified signal (1575.42 MHz) to a 4.092 MHz differential IF signal. The current chip provides 3 configurations to choose from, which are high-gain LNA, mid-gain LNA and low-gain LNA. The high-gain LNA is used for low-cost solution without external LNA. The mid-gain LNA provides moderate noise figure. The low-gain LNA offers extremely low RF current consumption but worst noise figure performance. In the application with external LNA, the external LNA gain ranging from 0 to 36 dB is recommended. The down-conversion mixer is single-ended passive mixer with current mode interface between the mixer and complex CSF.

### 4.2 VCO/Synthesizer

The entire frequency synthesizer includes crystal oscillator, VCO, divider, phase frequency detector (PFD), charge pump (CP) and loop filter which are all integrated on the MT3336 chip. Upon power-on, VCO is auto-calibrated to its required sub-band. The synthesizer has two topologies (integer-N or fractional-N) selectable through the base band control.

Integer-N synthesizer only supports 16.368 MHz frequency. Other clock modes from 12.6 MHz up to 40 MHz are supported by fractional-N synthesizer, together with a sigma-delta modulator (SDM) and multi-modulus divider (MMD).

### 4.3 IF CSF

The down converted IF signal from the mixer output passes through a band pass CSF. Centered at 4.092 MHz, the filter rejects out-of-band (10 MHz) interferences by more than 20 dB and has a pass band ripple of < 0.5 dB. The current-mode mixer and filter also provide a 32 dB pass band gain together to improve noise figure.

### 4.4 PGA

The PGA has approximately 40 dB of gain control range with approximately 1.6 dB per step. The maximum gain is around 40 dB. HPF circuits are implemented among PGAs to remove DC offset quickly.

### 4.5 ADC

The differential IF signal is being quantized by a 4-bit ADC. The sampling clock can be provided from OSC direct path or using LO/96.

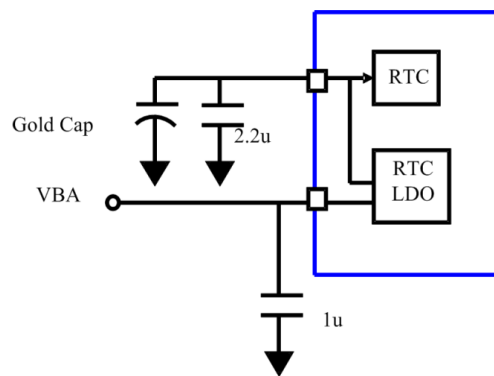
## 5 MT3336 Digital Part

### 5.1 Boot ROM

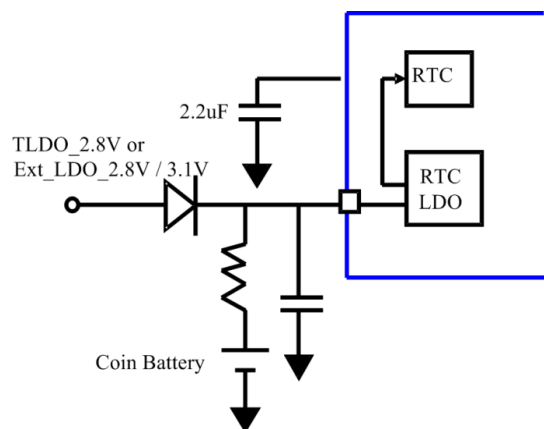
The embedded boot ROM provides a function of loading a set of user code through the host interface into SRAM. The host interface (UART/SPI/I2C) is decided by strap control.

### 5.2 Battery backed-up memory

MT3336 provides very low leakage (about 5 uA in the backup mode) battery backed-up memory, which contains all the necessary GPS information for quick start-up and a small amount of user configuration variables. There is a built-in 1.2 volts LDO for RTC domain and it can be bypassed while an external LDO is applied. The RTC LDO is a voltage regulator having very low quiescent current, and typical quiescent current < 2.5 uA. The small ceramic capacitor can be used as the output capacitor, and the stable operation region ranges from very light load (~=0) to about 3 mA.



**Figure 5-1: RTC with internal RTC LDO application circuit 1**



**Figure 5-2: RTC with internal RTC LDO application circuit 2**

### 5.3 SMPS

A built-in switching mode power supply provides 1.8 volts power supply for the digital 1.2 volts CLDO and RF input power. In the active mode, SMPS is operated in the PWM mode. In the power saving mode, SMPS is operated with reduced switching frequency in the PFM mode. The recommended L/C value is 4.7 uH / 10 uF.

### 5.4 Timer function

The timer function supports a time tick generation of 31.25 ms resolution. With the 24-bit counter, the period of timer is from 31.25 ms to 524,287 s. The “TIMER” pin outputs signal 1'b0 during the timer period and becomes an input pin after time-out. The power control function for the system can be executed by connecting this pin to an external LDO controller and adding external pull-high circuit.

### 5.5 GPIO in RTC domain

The “32K\_OUT” pin in RTC domain can output 32.768 KHz clock which can be used to support low clock rate operation mode for some applications or peripherals that need an external clock source. This pin can also be programmed to be an input pin to receive the signal from an external accelerator sensor IC to be the wake-up signal of MT3336 when it is in the low-power mode.

### 5.6 Low power detection

A low power detection circuit is implemented. Whenever the independent power source (AVDD12\_RTC) becomes low voltage, the low power detection circuit will detect this condition and use an indicator signal (output high in normal condition and low in low-power condition) to reflect this condition.

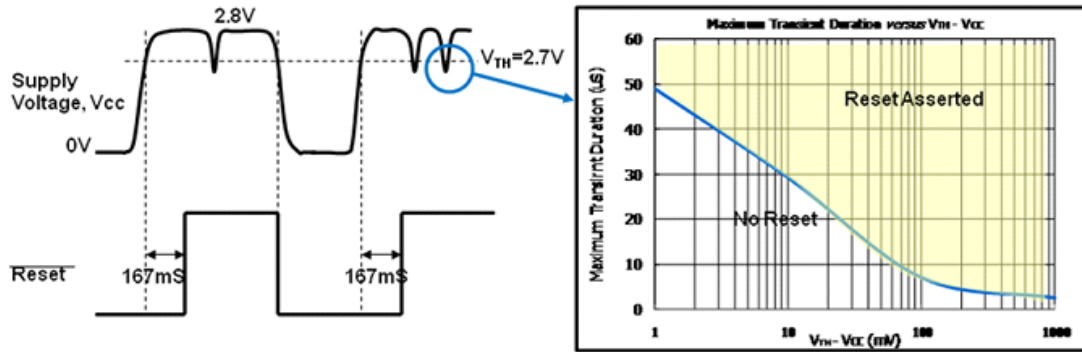
### 5.7 Clock module

The clock module generates all internal clocks required by processor, correlator, internal memory, bus interface and so on. The referenced input clock is generated from the RF block. For system flexibility and maximum power saving, it supports various power management modes.

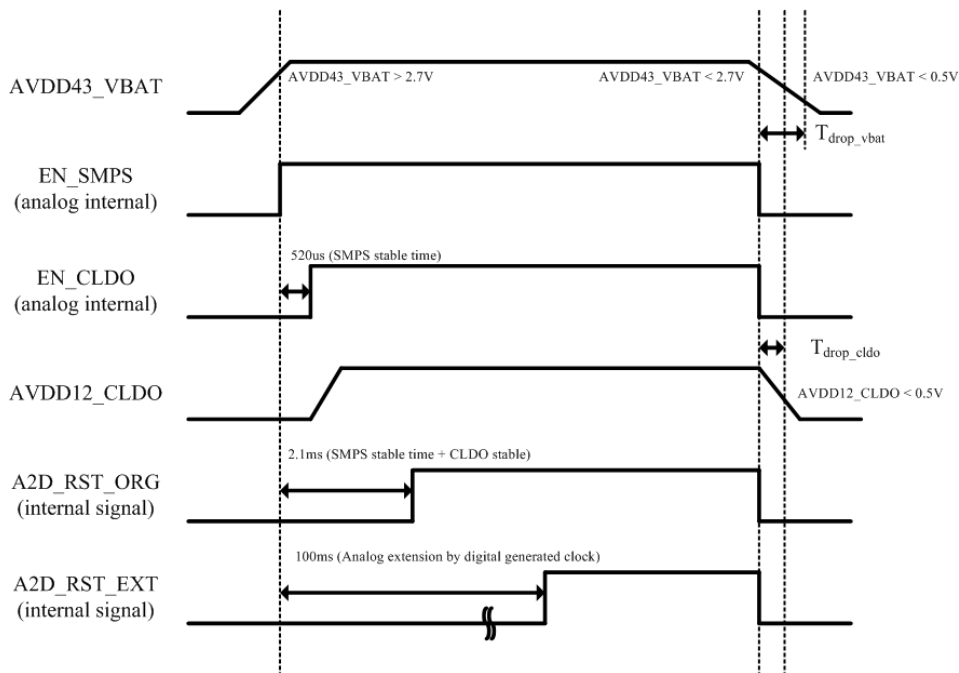
### 5.8 Reset controller

The built-in reset controller generates reset signals for all digital blocks. It has power-on reset feature and hardware trapping function. The power-on reset level is  $2.7 \pm 0.1$  volts. The software reset function for different circuit blocks are also included for flexible applications.

In Figure 5-4, the voltage drop time  $T_{drop\_vbat}$  and  $T_{drop\_cldo}$  depend on the capacitance connection of their power net. But  $T_{drop\_vbat} > T_{drop\_cldo}$  should be guaranteed for the correct operation of reset behavior during power off sequence. It is strongly recommend using external LDOs without output discharged function or make sure  $T_{drop\_vbat} > 100$  ms.



**Figure 5-3: Power on reset diagram**



**Figure 5-4: Power on/off reset behavior**

## 5.9 Host interface

MT3336 supports 3 different host interfaces, which are UART, SPI, and I2C. The interface used as the host interface is determined by strap pins.

### 5.9.1 UART

UART is the abbreviation of “Universal Asynchronous Receiver/Transmitter”. MT3336 has 3 full duplex serial ports. It is used for serial data communication. A UART converts bytes of data to and from asynchronous start-stop bit streams represented as binary electrical impulses.

There are several functions in MT3336 related to UART communication, such as UART data transmission/receive and aiding information input from host processor. In general, UART0 is as measurement data output and PMTK command input, UART1 as RTCM input. You can adjust the UART2 port as desired. The receiver (RX) and transmitter (TX) side of every port contains a 16-byte



FIFO, but only UART0 has 256 bytes of URAM. The bit rates are selectable and range from 4.8 to 921.6 kbps. UART provides signal or message outputs.

### 5.9.2 SPI

The serial peripheral interface port manages the communication between digital BB and external devices. MT3336 supports both master and slave modes. Only 4 bytes of register in the master mode can be transferred. The slave has 4-byte-register mode or URAM mode. In the URAM mode, the transmitted and received data size is 256 bytes. The clock phase and clock polarity are selectable. MT3336 supports manual or automatic indicator for data transfer in the slave mode.

### 5.9.3 I2C

The I2C interface is mainly connected to external devices. MT3336 supports multi-master and slave modes. Both modes have 256-byte URAM mode and 8-byte FIFO mode for transmitting and receiving data. The multi-master mode supports 7-bit or 10-bit address mode, up to 400 Kb/s fast mode, and 3.4 Mb/s high-speed mode. In additions, MT3336 supports manual or automatic indicator for data transfer in the slave mode. Device addresses in the slave mode are programmable and support fast mode and high-speed mode data transmission and reception.

## 5.10 Interrupt control unit

The interrupt control unit manages all internal and external sources of interrupts, which include timer, watch-dog, all interfaces such as UART, I2C and SPI and external user interrupt pins. These interrupt sources can be wake-up events in the power saving mode.

## 5.11 GPIO unit

GPIO is the abbreviation of "General-Purpose Input/Output". MT3336 supports a variety of peripherals through maximum 15 GPIO programmable ports. The unit manages all GPIO lines and supports a simple control interface. GPIO provides signal or message outputs.

## 5.12 PPS

The PPS (Pulse Per Second) signal is provided through designated output pin for many external applications. The pulse is not only limited to being active every second but also allowed to set up the required duration, frequency and active high/low by programming user-defined settings.

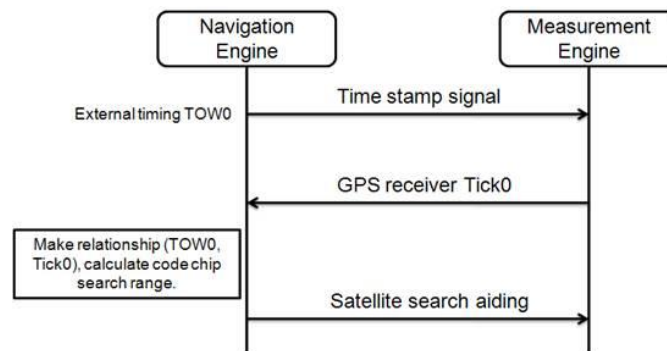
## 5.13 ECLK

ECLK is a clock input pin for introducing an external clock signal to MT3336 and obtaining the relation between the external clock and GPS local clock. With precise external clock input, the clock drift of the GPS local clock can be correctly estimated. Therefore, the Doppler search range is narrowed down accordingly. The technology is beneficial to speeding up the satellite acquisition process. Particularly in the cold start case, due to limited priori information about the satellite's location and local clock uncertainty, a receiver will execute a search in full frequency range. Consequently, a longer acquisition time is expected. However, the ECLK technology is able to reduce the frequency

uncertainty so that the search process will be completed in a short time. Efficient acquisition and lower power consumption are attained by the ECLK technology.

### 5.14 SYNC

SYNC is a time stamp signal input pin for introducing an external timing to the GPS receiver and obtaining the relation between the external timing and the GPS receiver local timing. With precise external timing input and the established relation, the GPS time of week (TOW) can be correctly estimated in the GPS receiver. The technology is beneficial for time to first fix (TTFF), particularly in weak signal environments. In hot starts, with priori information about the GPS receiver's location and satellite ephemeris data, the GPS receiver uses the correct GPS TOW to accurately predict the signal code chip/phase. Therefore, the code search range can be narrowed down accordingly. Hence, fast TTFF is achieved by the SYNC technology.



**Figure 5-5: Flow diagram of SYNC function**

### 5.15 Power scheme

- Internal SMPS is used as the source power of the internal RF/BB LDO. It is also used as 1.8 volts I/O power. The internal SMPS can switch to the LDO mode to supply power to each of the about block
- External LDO or VBAT can be used as the main power. The minimum/maximum input voltage of AVDD43\_VBAT and AVDD43\_SMPS is 2.8/4.3 volts.
- The power-on reset voltage threshold of AVDD43\_VBAT is  $2.7 \pm 0.1$  volts. The maximum TLDO drop out voltage at half load (25 mA ) is 0.25 volts. If one external LDO is used to provide power to MT3336, the 3.3 volts external LDO will be recommended after taking TLDO drop-out into consideration.
- The power efficiency in SMPS mode will be better than that in the internal LDO mode.
- I/O supports 1.8 and 2.8 volts. The power comes from SMPS output for 1.8 volts application or TLDO output (AVDD28\_TLDO) for 2.8 volts application.
- TCXO power is from AVDD28\_TLDO\_SW with an internal MUX to select 2.8 volts from AVDD28\_TLDO or 1.8 volts from AVDD28\_CLDO by setting up power-on strap.
- RTC LDO input power comes from AVDD28\_TLDO and uses coin battery as the backup battery. A schottky diode is usually used to avoid leakage from coin battery to TLDO.

- Here are 3 power schemes: low power (Figure 5-6), low cost (Figure 5-7) and external PMU (Figure 5-8).
- In Figure 5-8, if 2.8V TCXO is used, AVDD28\_CLDO should be open for saving power.

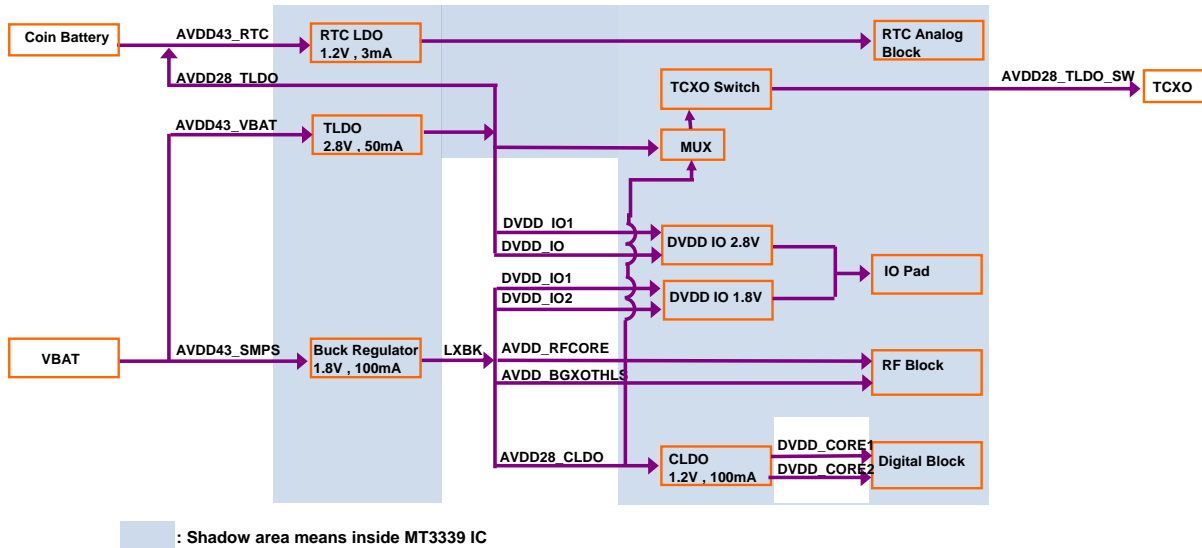


Figure 5-6: Power supply connection (low power)

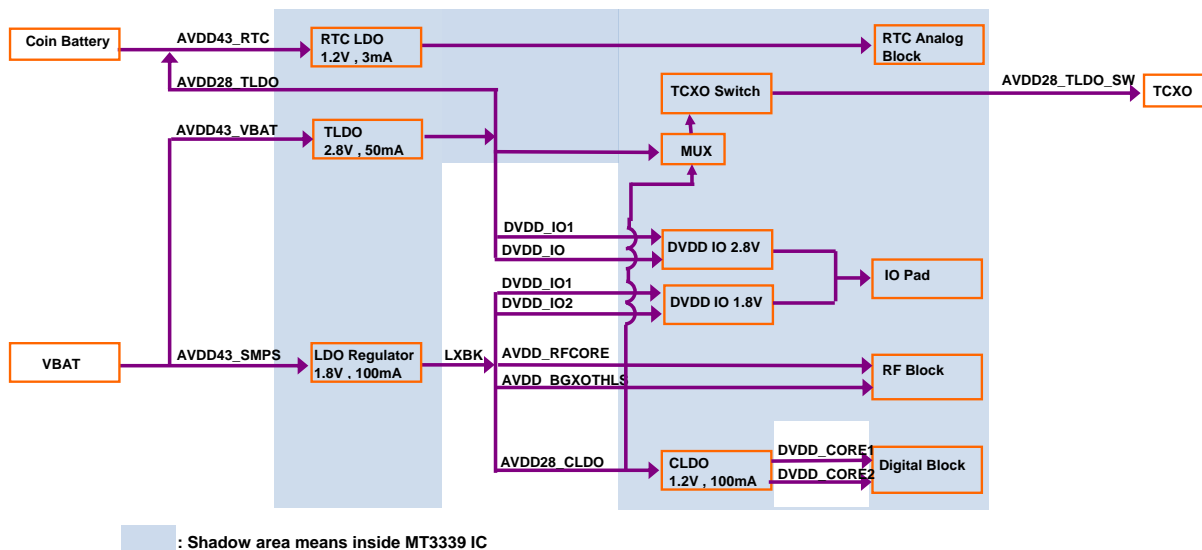


Figure 5-7: Power supply connection (low cost)

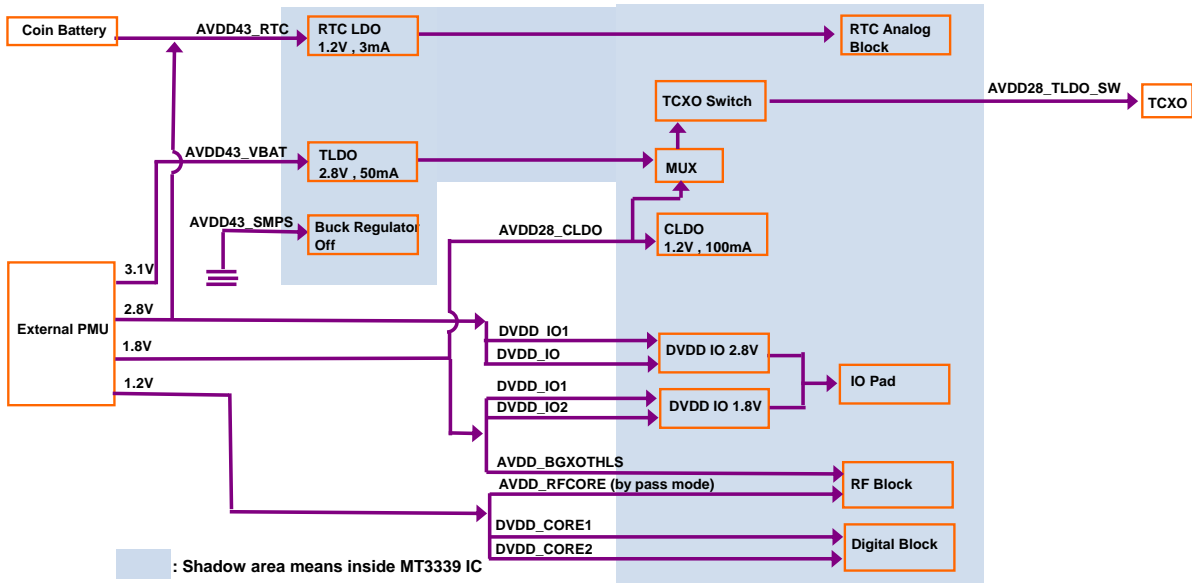


Figure 5-8: Power supply connection (external LDO)

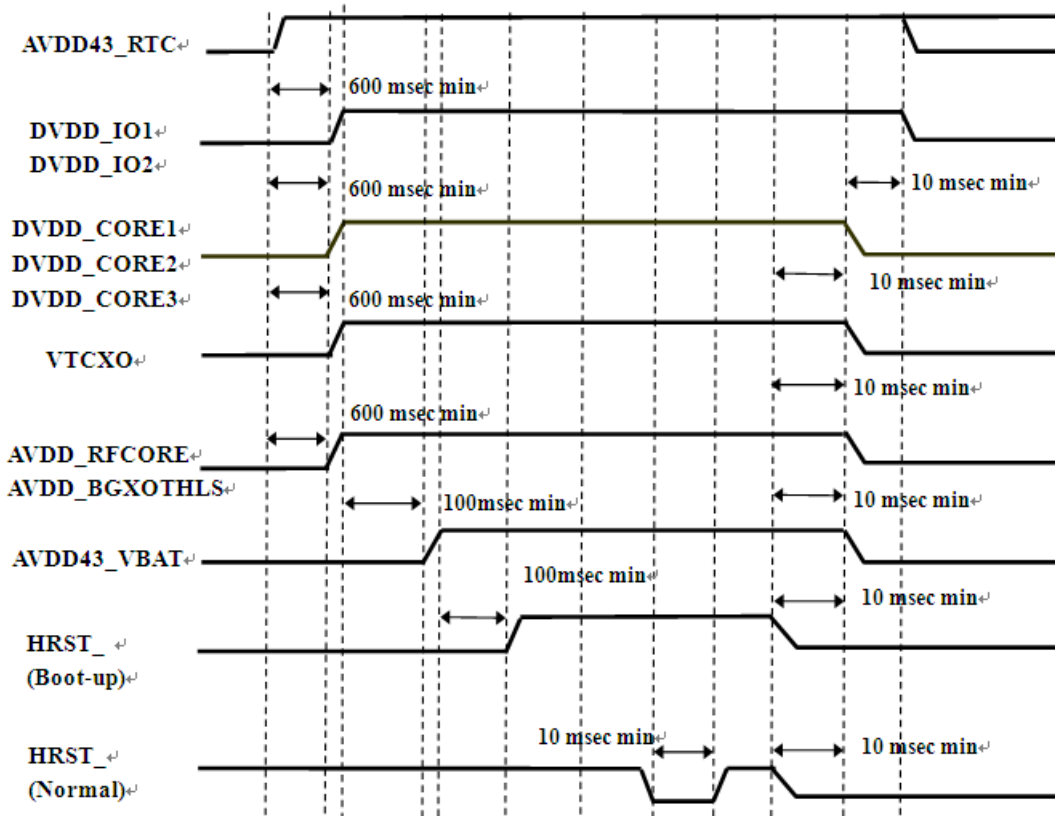


Figure 5-9: Power up sequence for external LDO mode

## 6 Electrical Characteristics

### 6.1 DC characteristics

#### 6.1.1 Absolute maximum ratings

Symbol	Parameter	Rating	Unit
AVDD43_SMPS	SMPS power supply	-0.3 ~ 4.3	V
AVDD43_VBAT	2.8 volts TLDO power supply	-0.3 ~ 4.3	V
AVDD28_CLDO	1.2 volts CLDO power supply	-0.3 ~ 3.08	V
DVDD_IO1 DVDD_IO2	IO 2.8/1.8 volts power supply	-0.3 ~ 3.6	V
DVDD_CORE1 DVDD_CORE2 DVDD_CORE3	Baseband 1.2 volts power supply	-0.3 ~ 1.32	V
AVDD43_RTC	RTC 1.2 volts LDO power supply	-0.3 ~ 4.3	V
AVDD_RFCORE	1.8 volts supply for RF core circuits	-0.3 ~ 3.08	V
AVDD_BGXOTHLS		-0.3 ~ 3.08	V
T <sub>STG</sub>	Storage temperature	-50 ~ +125	°C
T <sub>A</sub>	Operating temperature	-45 ~ +85	°C

#### 6.1.2 Recommended operating conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
AVDD43_SMPS	SMPS power supply	2.8	3.3	4.3	V
AVDD43_VBAT	2.8 volts TLDO power supply	2.8	3.3	4.3	V
DVDD_CORE1 DVDD_CORE2 DVDD_CORE3	1.2 volts baseband core power	1.08	1.2	1.32	V
DVDD_IO1	2.8 volts digital I/O power	2.52	2.8	3.08	V
DVDD_IO2	1.8 volts digital I/O power	1.62	1.8	1.98	V
AVDD_RFCORE	1.2 volts supply for RF core circuits in bypass mode	1.14	1.2	1.26	V
	1.8 volts supply for RF core circuits in LDO mode	1.62	1.8	3.08	V
AVDD_BGXOTHLS		1.62	1.8	3.08	V
T <sub>A</sub> T <sub>j</sub>	Operating temperature	-40	25	85	°C
	Commercial junction operating temperature	0	25	115	°C
	Industry junction operating temperature	-40	25	125	°C

### 6.1.3 General DC characteristics

Symbol	Parameter	Condition	Min.	Max.	Unit
I <sub>IL</sub>	Input low current	No pull-up or down	-1	1	uA
I <sub>IH</sub>	Input high current	No pull-up or down	-1	1	uA
I <sub>OZ</sub>	Tri-state leakage current		-10	10	uA

### 6.1.4 DC electrical characteristics for 2.8 volts operation

Symbol	Parameter	Condition	Min.	Max.	Unit
V <sub>IL</sub>	Input lower voltage	LVTTTL	-0.3	0.8	V
V <sub>IH</sub>	Input high voltage		2.0	3.6	V
V <sub>T-</sub>	Schmitt trigger negative going threshold voltage	LVTTTL	0.8	1.6	V
V <sub>T+</sub>	Schmitt trigger positive going threshold voltage		1.6	2.0	V
V <sub>OL</sub>	Output low voltage	I <sub>OL</sub>   = 1.6 ~ 14 mA	-0.3	0.4	V
V <sub>OH</sub>	Output high voltage	I <sub>OH</sub>   = 1.6 ~ 14 mA	2.4	VDD28 + 0.3	V
R <sub>PU</sub>	Input pull-up resistance	PU = high, PD = low	40	190	KΩ
R <sub>PD</sub>	Input pull-down resistance	PU = low, PD = high	40	190	KΩ

### 6.1.5 DC electrical characteristics for 1.8 volts operation

Symbol	Parameter	Condition	Min.	Max.	Unit
V <sub>IL</sub>	Input lower voltage	LVTTTL	-0.18	0.4	V
V <sub>IH</sub>	Input high voltage		1.5	1.98	V
V <sub>T-</sub>	Schmitt trigger negative going threshold voltage	LVTTTL	0.44	0.88	V
V <sub>T+</sub>	Schmitt trigger positive going threshold voltage		0.88	1.1	V
V <sub>OL</sub>	Output low voltage	I <sub>OL</sub>   = 1.6 ~ 14 mA	-0.18	0.4	V
V <sub>OH</sub>	Output high voltage	I <sub>OH</sub>   = 1.6 ~ 14 mA	1.4	VDD18 + 0.18	V
R <sub>PU</sub>	Input pull-up resistance	PU = high, PD = low	40	190	KΩ
R <sub>PD</sub>	Input pull-down resistance	PU = low, PD = high	40	190	KΩ

### 6.1.6 DC electrical characteristics for 1.2 volts operation (for TIMER and 32K\_OUT)

Symbol	Parameter	Condition	Min.	Max.	Unit
V <sub>IL</sub>	Input lower voltage	LVTTTL	-0.3	0.54	V
V <sub>IH</sub>	Input high voltage		0.66	3.6	V
V <sub>T-</sub>	Schmitt trigger negative going threshold voltage	LVTTTL	0.24	0.46	V

Symbol	Parameter	Condition	Min.	Max.	Unit
$V_{T+}$	Schmitt trigger positive going threshold voltage		0.64	0.9	V
$V_{OL}$	Output low voltage	$ I_{OL}  = 0.9 \text{ mA}$		0.42	V
$V_{OH}$	Output high voltage	$ I_{OH}  = 0.9 \text{ mA}$	0.78		V
$R_{PU}$	Input pull-up resistance	PU = high, PD = low	130	560	K $\Omega$
$R_{PD}$	Input pull-down resistance	PU = low, PD = high	130	560	K $\Omega$

## 6.2 Analog related characteristics

### 6.2.1 SMPS DC characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Note
AVDD43_SMPS	SMPS input supply voltage	2.8	3.3	4.3	V	
LXBK	SMPS output	1.71	1.8	1.95	V	
$I_{max}$	SMPS current limit	100			mA	
$I_{cc}$	For normal operation current		20	70	mA	
$\Delta V_{PWM}$	Ripple of PWM mode			40	mV	With L=4.7uH, C=10uF
$\Delta V_{PFM}$	Ripple of PFM mode			90	mV	With L=4.7uH, C=10uF
$I_q$	Quiescent current		50		uA	

### 6.2.2 TCXO LDO DC characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Note
AVDD43_VBAT	TCXO LDO input supply voltage	2.8	3.3	4.3	V	Will change to bypass mode under 3.1 volts
AVDD28_TLDO	TCXO LDO output	2.7	2.8	2.9	V	
$I_{max}$	TCXO LDO current limit	50			mA	
$I_{cc}$	For normal operation current		1	30	mA	Not include external devices
	PSRR-30 KHz		40		dB	$C_o = 1 \text{ uF}$ , ESR = 0.05, $I_{load} = 25 \text{ mA}$
	Load regulation		10		mV	
$I_q$	Quiescent current		50		uA	

### 6.2.3 TCXO SWITCH DC characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Note
AVDD28_TLDO_SW	TCXO switch output voltage @ TCXO switch input = AVDD28_TLDO	2.66	2.8	2.9	V	

Symbol	Parameter	Min.	Typ.	Max.	Unit	Note
AVDD28_TLDO_SW	TCXO switch output voltage @ TCXO switch input = AVDD28_CLDO	1.71	1.8	1.89	V	
I <sub>max</sub>	TCXO SWITCH current limit	2			mA	

### 6.2.4 1.2 volts core LDO DC characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Note
AVDD28_CLDO	1.2 volts LDO input supply voltage	1.62	1.8	3.08	V	
AVDD12_CLDO	1.2 volts LDO output	1.1	1.2	1.3	V	
I <sub>max</sub>	1.2 volts LDO current limit	100			mA	
I <sub>cc</sub>	For normal core operation current		15	85	mA	
	Load regulation		10		mV	
I <sub>q</sub>	Quiescent current		20		uA	

### 6.2.5 1.2 volts RTC LDO DC characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Note
AVDD43_RTC	RTC LDO input supply voltage	2	2.8	4.3	V	
AVDD12_RTC	RTC LDO output	1.08	1.2	1.32	V	
I <sub>max</sub>	RTC LDO current limit	3			mA	
I <sub>cc</sub>	For normal RTC operation current			2.7	mA	
I <sub>q</sub>	Quiescent current		2		uA	
I <sub>leak</sub>	Leakage current		10		uA	Including LDO and RTC domain circuit

### 6.2.6 32 KHz crystal oscillator (XOSC32)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Note
AVDD12_RTC	Analog power supply	1.08		1.32	V	
Dcyc	Duty cycle		50		%	

## 6.3 RF related characteristics

### 6.3.1 DC electrical characteristics for RF part

Symbol	Parameter	Min.	Typ.	Max.	Unit
I <sub>cc</sub>	Total supply current: High gain LNA		13.5	14.8	mA



Symbol	Parameter	Min.	Typ.	Max.	Unit
	Total supply current: Middle gain LNA Total supply current: Low gain LNA (Total supply current = RX + SX + LDO current)		8.5 7.3	9.4 8	
I <sub>cc</sub> (STAND-BY)	Only the PLL, oscillator and regulator are kept powered up.		3.5		mA
I <sub>cc</sub> (DOZE)	Only the oscillator and regulator are kept powered up.		0.6		mA
I <sub>cc</sub> (Off)	Power-down state current			2	μA

### 6.3.2 RX chain from LNA to PGA, before ADC

Parameter	Condition	Min.	Typ.	Max.	Unit
Noise figure	SOC on: High gain LNA SOC on: Mid gain LNA SOC on: Low gain LNA		2 2.5 5.5	2.5 3 6	dB
Image rejection ratio			30		dB
V <sub>cc</sub>		1.14	1.2	1.26	V
Current consumption	RX chain only (LNA, mixer, CSF, PGA, divider, ADC)		5.5		mA

### 6.3.3 Receiver front-end part (LNA only)

Parameter	Condition	Min.	Typ.	Max.	Unit
RF input frequency			1.57542		GHz
LO frequency			1.57132		GHz
Input return loss			-10		dBm
Voltage gain -- Av	High gain LNA Mid gain LNA Low gain LNA	27.5 25.5 16	29 27 18		dB
Noise figure	High gain LNA Mid gain LNA Low gain LNA		1.5 2 5	2 2.5 6	dB

### 6.3.4 Mixer and channel selection filter (CSF)

Parameter	Condition	Min.	Typ.	Max.	Unit
Filter type	3 <sup>rd</sup> -order butterworth polyphase bandpass (Note 1)				
Voltage	Supply voltage	1.14	1.2	1.26	V
BW <sub>3dB</sub>	3dB bandwidth		2.5/4		MHz
Filter frequency response (2.5M/4M)	Rejection band attenuation @ f = 3 MHz @ f = 10 MHz @ f = 15 MHz @ f > 20 MHz		23/12 54/45 65/54 72/60		dB

Voltage gain -- Av	High gain mixer + CSF Low gain mixer + CSF		32 20		dB
--------------------	---	--	----------	--	----

### 6.3.5 Programmable gain amplifier (PGA)

Parameter	Condition	Min.	Typ.	Max.	Unit
Supply voltage	Supply voltage	1.14	1.2	1.26	V
Center frequency	Centre frequency		4.092		MHz
Voltage gain	Voltage gain	0		40	dB
Gain step	Gain step (5 bits)		1.6		dB

### 6.3.6 2-bit and 4-bit quantizer (ADC)

Parameter	Condition	Min.	Typ.	Max.	Unit
Supply voltage	Supply voltage	1.14	1.2	1.26	V
Input sampling clock	Operating frequency		16.368	30	MHz
Input signal frequency	Input signal center frequency		4.092		MHz
Resolution			4		Bits

### 6.3.7 Integrated synthesizer

Symbol	Parameter	Min.	Typ.	Max.	Unit
F <sub>osc</sub>	VCO oscillation frequency		3,142.6 56		MHz
V	Tuning voltage range	0.2		V <sub>cc</sub> -0.2	V
DIV	Programmable divider ratio	32		127	
T <sub>start</sub>	Circuit start-up time			100	μs

### 6.3.8 Crystal oscillator (XO)

Symbol	Parameter	Min.	Typ.	Max.	Unit
F <sub>tcxo</sub>	TCXO oscillation frequency	12.6	16.368	40	MHz
V <sub>tcxo</sub>	TCXO output swing	0.8	1.2		V <sub>pp</sub>

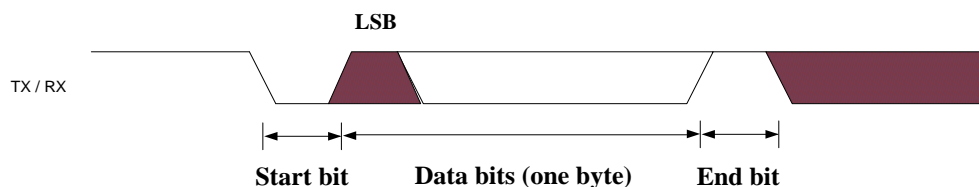
## 7 Interface Characteristics

### 7.1 RS-232 interface timing

Baud rate required (bps)	Programmed baud rate (bps)	Baud rate error (%)	Baud rate error (%) <sup>3</sup>
4,800	4,800.000	0.0000	0.002
9,600	9,600.000	0.0000	0.002
14,400	14,408.451	0.0587	0.0567
19,200	19,164.319	0.0587	0.0567
38,400	38,422.535	0.0587	0.0567
57,600	57,633.803	0.0587	0.0567
115,200	115,267.606	0.0587	0.0567
230,400	230,535.211	0.0587	0.0567
460,800	454,666.667	-1.3310	-1.3330
921,600	909,333.333	-1.3310	-1.3330

Notes:

1. UART baud-rate settings with UART\_CLK frequency = 16.368 MHz (UART\_CLK uses the reference clock of the system).
2. The baud rate error is optimized. Each baud rate needs to adjust counter to obtain the optimized error.
3. Suppose TCXO frequency is exactly at 16.368 MHz. If TCXO has 20 PPM, the error will raise slightly.



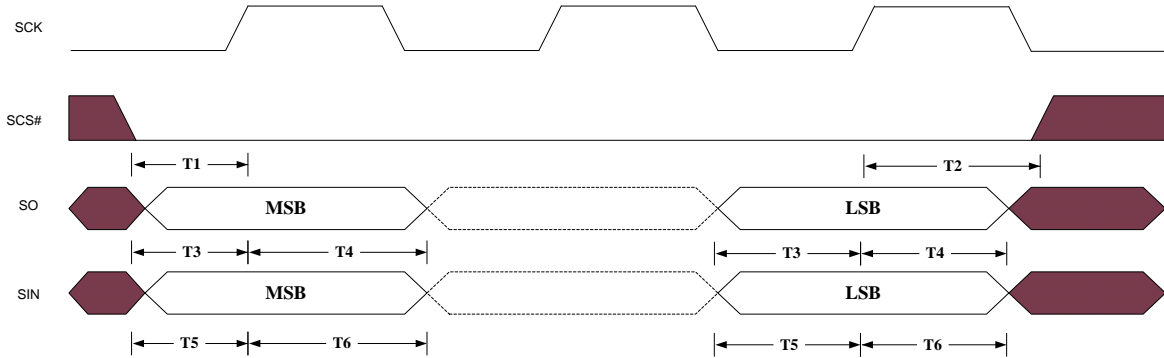
**Figure 7-1: Timing diagram of RS-232 interface**

### 7.2 SPI interface timing

Description	Symbol	Min.	Max.	Unit	Note
SCS# setup time	T1	0.5T	-	ns	1
SCS# hold time	T2	0.5T	-	ns	1
SO setup time	T3	0.5T - 3t	0.5T - 2t	ns	1, 2
SO hold time	T4	0.5T + 2t	0.5T + 3t	ns	1, 2
SIN setup time	T5	3t	-	ns	1, 2
SIN hold time	T6	10	-	ns	1

Notes:

1. The condition of SPI clock cycle (T) is  $(\text{SPI\_IPLL}/\text{SPI\_IPLL}/12)$  MHz ~  $(\text{rf\_clk}/1,020)$  MHz.
2. t indicates the period of SPI controller clock, which is SPI\_IPLL clock or rf\_clk.

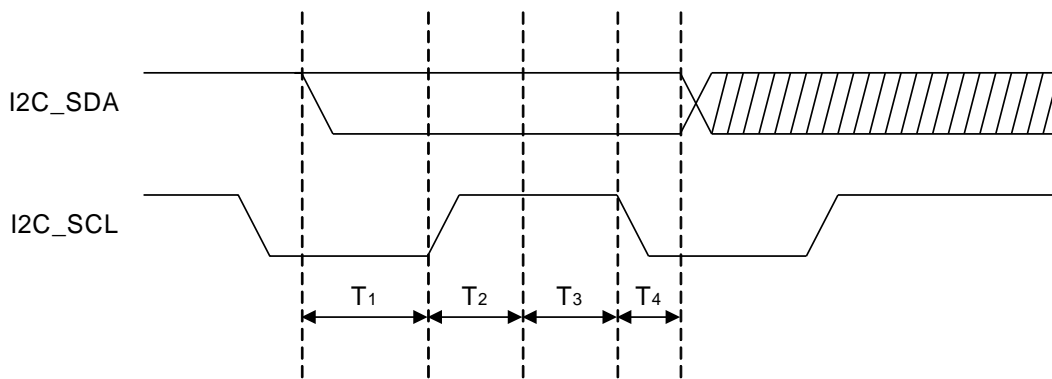


**Figure 7-2: Timing diagram of SPI interface**

### 7.3 I2C interface timing

Symbol	Period
T1	$(\text{MM\_CNT\_PHASE\_VAL0}+1)/\text{TCXO\_CLK}$
T2	$(\text{MM\_CNT\_PHASE\_VAL1}+1)/\text{TCXO\_CLK}$
T3	$(\text{MM\_CNT\_PHASE\_VAL2}+1)/\text{TCXO\_CLK}$
T4	$(\text{MM\_CNT\_PHASE\_VAL3}+1)/\text{TCXO\_CLK}$

Note: The condition of I2C clock cycle (I2C\_CLK) is  $(\text{TCXO\_CLK}/4)$  MHz ~  $(\text{TCXO\_CLK}/(\text{MM\_CNT}+4))$  MHz. The MM\_CNT is sum of MM\_CNT\_PHASE\_VAL0, MM\_CNT\_PHASE\_VAL1, MM\_CNT\_PHASE\_VAL2 and MM\_CNT\_PHASE\_VAL3 in full speed mode.

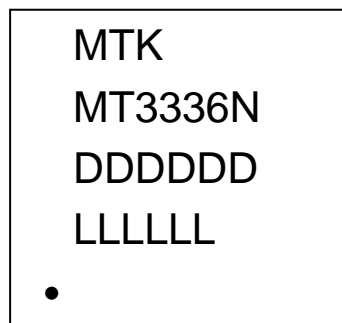


**Figure 7-3: Timing diagram of HOST I2C interface**

## 8 Package Description

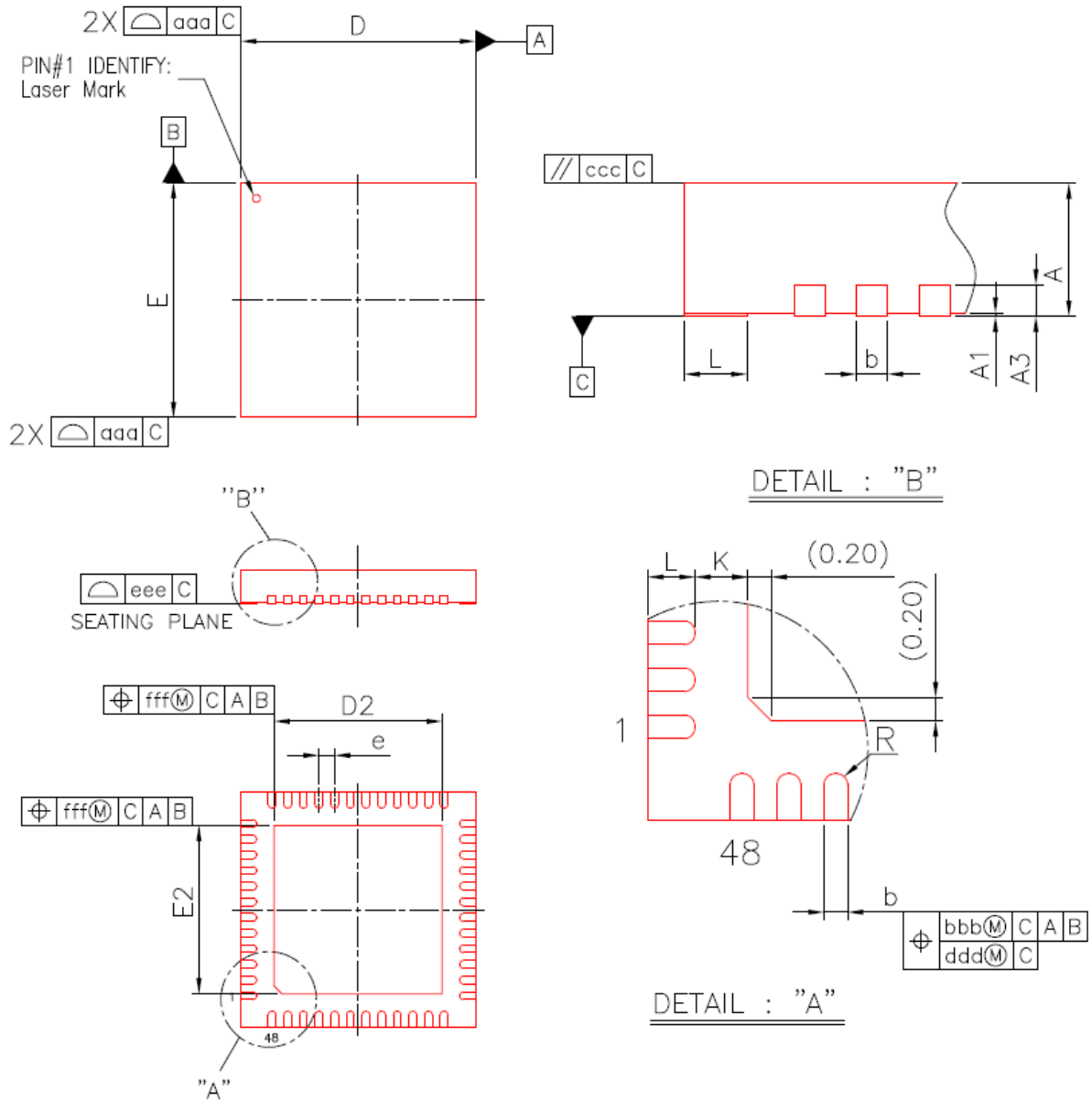
---

### 8.1 Top mark



N : QFN package  
DDDDDD : Date code  
LLLLLL : Lot number

## 8.2 Package dimensions



L/F	Exposed Pad Size						Internal Pad Size					
	Dimension in mm			Dimension in inch			Dimension in mm			Dimension in inch		
	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX
D2/E2	4.15	4.30	4.45	0.163	0.169	0.175	4.45	4.60	4.75	0.175	0.181	0.187

Symbol	Dimension in mm			Dimension in inch		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.85	0.90	0.031	0.033	0.035
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D/E	5.90	6.00	6.10	0.232	0.236	0.240
e	0.40 BSC			0.016 BSC		
L	0.30	0.40	0.50	0.012	0.016	0.020
K	0.20	---	---	0.008	---	---
R	0.075	---	---	0.003	---	---
aaa	0.10			0.004		
bbb	0.07			0.003		
ccc	0.10			0.004		
ddd	0.05			0.002		
eee	0.08			0.003		
fff	0.10			0.004		

NOTE:

1. CONTROLLING DIMENSION : MILLIMETER
2. REFERENCE DOCUMENT: JEDEC MO-220.

**ESD CAUTION**

MT3336 is ESD (electrostatic discharge) sensitive device and may be damaged with ESD or spike voltage. Although MT3336 is with built-in ESD protection circuitry, please handle with care to avoid permanent malfunction or performance degradation.

**Use of the GPS Data and Services at the User's Own Risk**

The GPS data and navigation services providers, system makers and integrated circuit manufactures ("Providers") hereby disclaim any and all guarantees, representations or warranties with respect to the Global Positioning System (GPS) data or the GPS services provided herein, either expressed or implied, including but not limited to, the effectiveness, completeness, accuracy, fitness for a particular purpose or the reliability of the GPS data or services.

The GPS data and services are not to be used for safety of life applications, or for any other application in which the accuracy or reliability of the GPS data or services could create a situation where personal injury or death may occur. Any use there with are at the user's own risk. The Providers specifically disclaims any and all liability, including without limitation, indirect, consequential and incidental damages, that may arise in any way from the use of or reliance on the GPS data or services, as well as claims or damages based on the contravention of patents, copyrights, mask work and/or other intellectual property rights.

No part of this document may be copied, distributed, utilized, and transmitted in any form or by any means without expressed authorization of all Providers. The GPS data and services are in part or in all subject to patent, copyright, trade secret and other intellectual property rights and protections worldwide.

MediaTek reserves the right to make change to specifications and product description without notice.